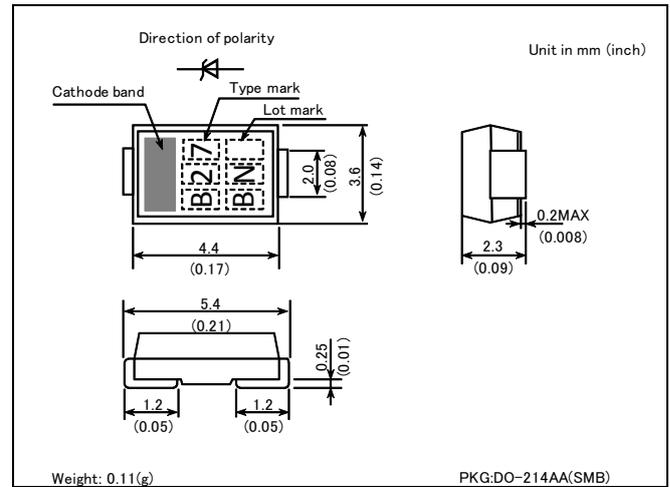


DAM2MB

FEATURES

- High transient reverse power capability suitable for protecting automobile electronic components etc.
- AEC-Q101 qualified
- RoHS compliant (Included RoHS exemption substance)

OUTLINE DRAWING



ABSOLUTE MAXIMUM RATINGS

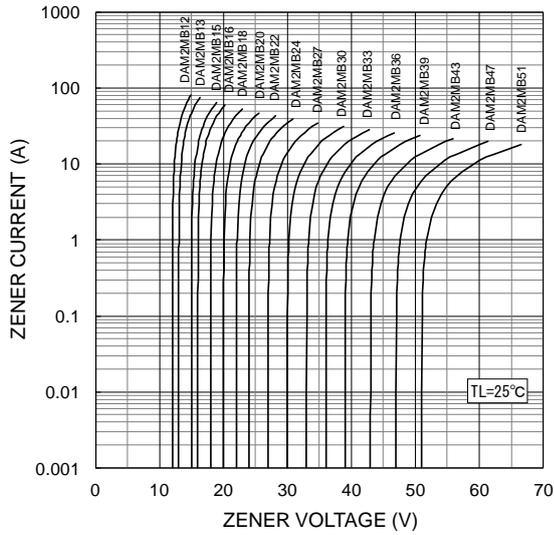
Items	Symbols	Units	Ratings
Non-Repetitive Peak Reverse One-Cycle Dissipation	P_{RSM}	W	600 (10/1000 μ s waveform, $T_j=25^\circ\text{C}$ start)
			1200 (Rectangular pulse $t=0.1\text{ms}$ $T_j=25^\circ\text{C}$ start)
Surge(Non-Repetitive) Forward Current	I_{FSM}	A	100 (8.3ms single half sine-wave, $T_j=40^\circ\text{C}$ start)
Operating Junction Temperature	T_j	$^\circ\text{C}$	-65 ~ +185
Storage Temperature	T_{stg}	$^\circ\text{C}$	-65 ~ +185
Stand-off Voltage	V_{RM}	V	Refer to characteristics column

CHARACTERISTICS($T_L=25^\circ\text{C}$)

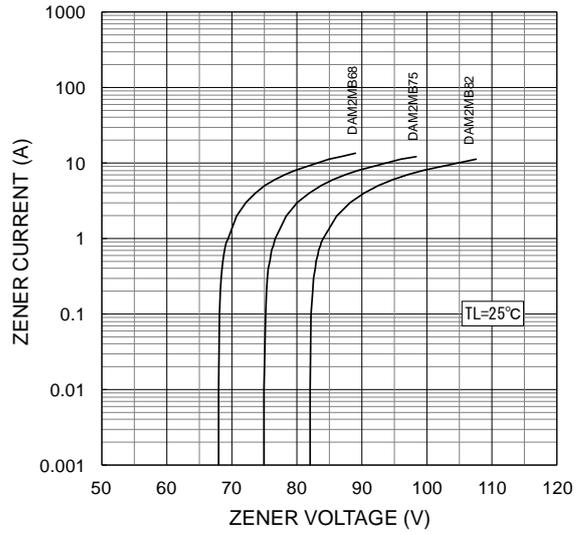
Type	Stand-off Voltage V_{RM} (V)	Characteristics				Maximum Peak Pulse Surge Current I_{PPM} (A)	Maximum Clamping Voltage at I_{PPM} V_C (V)
		Zener Voltage V_z (V)		Test Current I_z (mA)	Maximum Reverse Leakage at V_{RM} I_{RRM} (μ A)		
		Minimum	Maximum				
DAM2MB12	9.7	11.4	12.7	1	5	34.7	17.3
DAM2MB13	10.5	12.4	14.1	1	5	31.6	19.0
DAM2MB15	12.1	13.5	15.6	1	1	27.3	22.0
DAM2MB16	12.9	15.3	17.1	1	1	25.5	23.5
DAM2MB18	14.5	16.8	19.1	1	1	22.6	26.5
DAM2MB20	16.2	18.8	21.2	1	1	20.6	29.1
DAM2MB22	17.8	20.8	23.3	1	1	18.8	31.9
DAM2MB24	19.4	22.7	25.6	1	1	17.3	34.7
DAM2MB27	21.8	25.1	28.9	1	1	15.3	39.1
DAM2MB30	24.3	28.0	32.0	1	1	13.8	43.5
DAM2MB33	26.8	31.0	35.0	1	1	12.6	47.7
DAM2MB36	29.1	33.4	38.6	1	1	11.5	52.0
DAM2MB39	31.6	36.1	41.9	1	1	10.6	56.4
DAM2MB43	34.8	39.8	46.2	1	1	9.7	61.9
DAM2MB47	38.0	43.3	50.7	1	1	8.9	67.7
DAM2MB51	41.3	46.9	55.1	1	1	8.1	74.0
DAM2MB68	55.1	61.2	74.8	1	1	6.1	98.0
DAM2MB75	60.7	67.5	82.5	1	1	5.6	107.6
DAM2MB82	66.4	73.8	90.2	1	1	5.1	117.9

DAM2MB

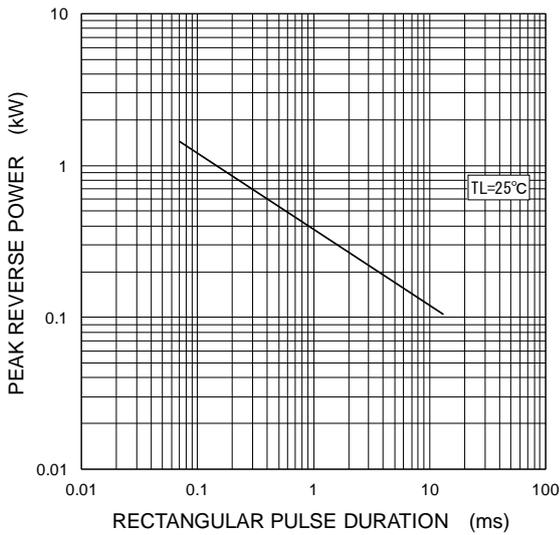
Typical zener characteristics (Vz : 12 – 51V)



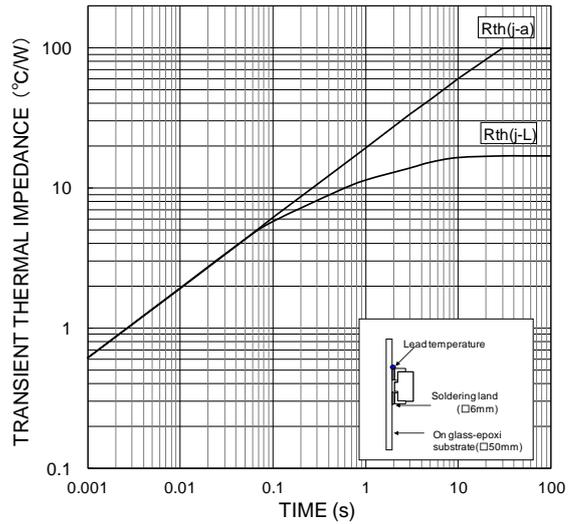
Typical zener characteristics (Vz : 68 – 82V)



Typical reverse power characteristics
(Rectangular pulse non-repetitive)



Transient thermal impedance



Precautions for Safe Use and Notices

If semiconductor devices are handled in inappropriate manner, failures may result.
For this reason, be sure to read "Precaution for Use" before use.



This mark indicates an item about which caution is required.



CAUTION

This mark indicates a potentially hazardous situation which, if not avoided, may result in minor or moderate injury and damage to property.



CAUTION

- (1) Regardless of changes in external conditions during use "absolute maximum ratings" should never be exceed in designing electronic circuits that employ semiconductors. In the case of pulse use, furthermore, "safe operating area(SOA)" precautions should be observed.
- (2) Semiconductor devices may experience failures due to accident or unexpected surge voltages. Accordingly, adopt safe design features, such as redundancy or prevention of erroneous action, to avoid extensive damage in the event of a failure.
- (3) In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, life-support-related medical equipment, fuel control equipment and various kinds of safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of user's fail-safe precautions or other arrangement. Or consult Hitachi's sales department staff.

(If a semiconductor device fails, there may be cases in which the semiconductor device, wiring or wiring pattern will emit smoke or cause a fire or in which the semiconductor device will burst)

NOTICES

1. This Datasheet contains the specifications, characteristics(in figures and tables), dimensions and handling notes concerning power semiconductor products (hereinafter called "products") to aid in the selection of suitable products.
2. The specifications and dimensions, etc. stated in this Datasheet are subject to change without prior notice to improve products characteristics. Before ordering, purchasers are advised to contact Hitachi's sales department for the latest version of this Datasheet and specifications.
3. In no event shall Hitachi be liable for any damage that may result from an accident or any other cause during operation of the user's units according to this Datasheet. Hitachi assumes to responsibility for any intellectual property claims or any other problems that may result from applications of information, products or circuits described in this Datasheet.
4. In no event shall Hitachi be liable for any failure in a semiconductor device or any secondary damage resulting from use at a value exceeding the absolute maximum rating.
5. No license is granted by this Datasheet under any patents or other rights of any third party or Hitachi Power Semiconductor Device, Ltd.
6. This Datasheet may not be reproduced or duplicated, in any form, in whole or in part, without the expressed written permission of Hitachi Power Semiconductor Device, Ltd.
7. The products (technologies) described in this Datasheet are not to be provided to any party whose purpose in their application will hinder maintenance of international peace and safety nor are they to be applied to that purpose by their direct purchasers or any third party. When exporting these products (technologies), the necessary procedures are to be taken in accordance with related laws and regulations.

Refer to the following website for the latest information. Consult Hitachi's sales department staff if you have any questions.

<http://www.hitachi-power-semiconductor-device.co.jp/en/>